

ABSTRACT

**METHOD OF PREPARING AN INTEGRATED CIRCUIT PACKAGE
FOR LASER MARKING**

5 The present invention advantageously provides a method of preparing an integrated circuit package for laser marking by a laser beam which is capable of providing lasting high contrast marks, but which does not render it necessary to change the compounds used in the preparation of the IC packages. The method comprises encapsulating an integrated circuit chip by an encapsulating transfer moulding process; and bonding a laser-markable film to a surface of the encapsulated integrated circuit chip to be marked.